

Special Issue

Virtual and Augmented Reality Technology in Education and Entertainment

Message from the Guest Editors

Among the many emerging technologies, virtual reality, augmented reality and mixed reality have gradually matured in recent years, and have been adopted by educators and industries. The common feature of these emerging technologies is that they are all assisted by digital content to help users conduct simulation or practical learning in difficult or dangerous application fields. This is enough to meet the important educational goals of today's applied science education. Under the overall global trend and context, this Special Issue invites experts and scholars who study new science and technologies to conduct more in-depth research on current and future applied science, and respond to the educational issues in the key medium of applied science.

Guest Editors

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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